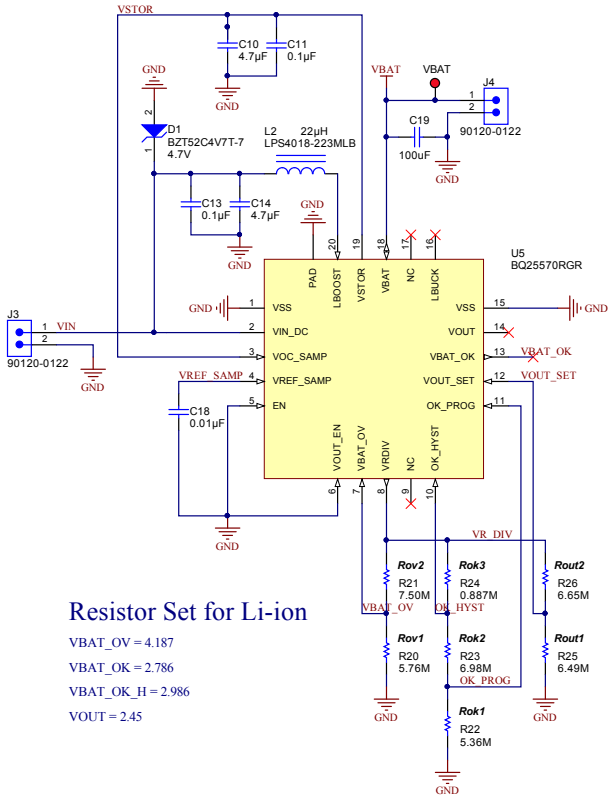


Resistor Set for Li-ion

VBAT_OV = 4.187

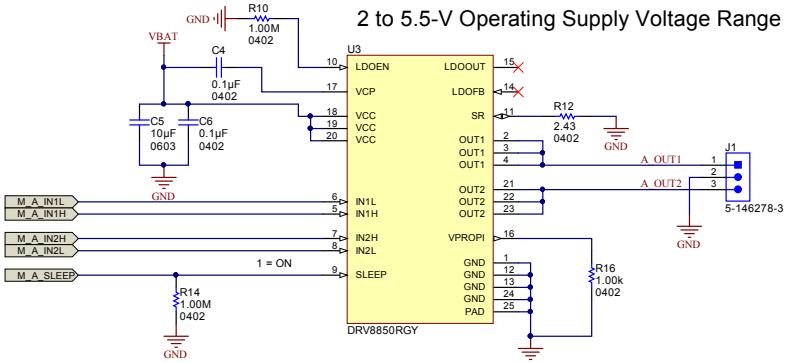
VBAT_OK = 2.786

VBAT_OK_H = 2.986

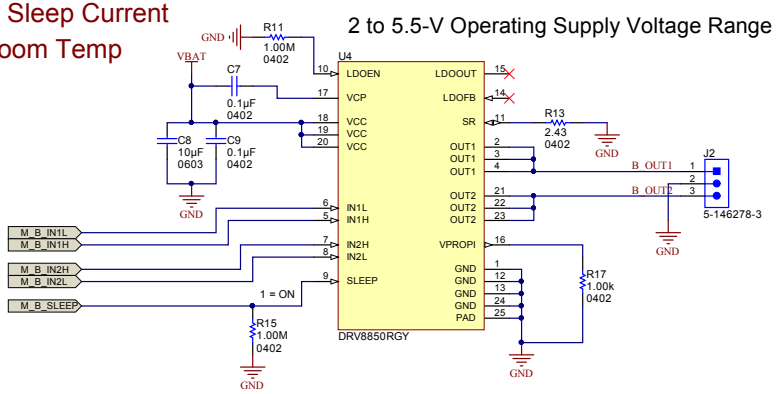
VOUT = 2.45

Orderable: N/A	Designed for:Public Release	Mod. Date: 7/23/2015
TID #:	Project Title:IoT Energy Harvesting BoosterPack	
Number: UTDBoosterPack Rev: Rev2.5	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant:[No Variations]	Sheet:2 of 3
Drawn By:	File: Page 3.SchDoc	Size: B
Engineer: Ahmad Rashed	Contact: http://www.ti.com/support	

TEXAS INSTRUMENTS
http://www.ti.com



Quiescent Current With Motor Driver off and LDO off, Sleep Current < 1.0uA at Room Temp



Orderable: N/A	Designed for:Public Release	Mod. Date: 7/23/2015
TID #:	Project Title:IoT Energy Harvesting BoosterPack	
Number: UTDBoosterPack	Rev: Rev2.5	Sheet Title:
SVN Rev: Not in version control	Assembly Variant:[No Variations]	Sheet:2 of 3
Drawn By:	File: Page 2.SchDoc	Size: B
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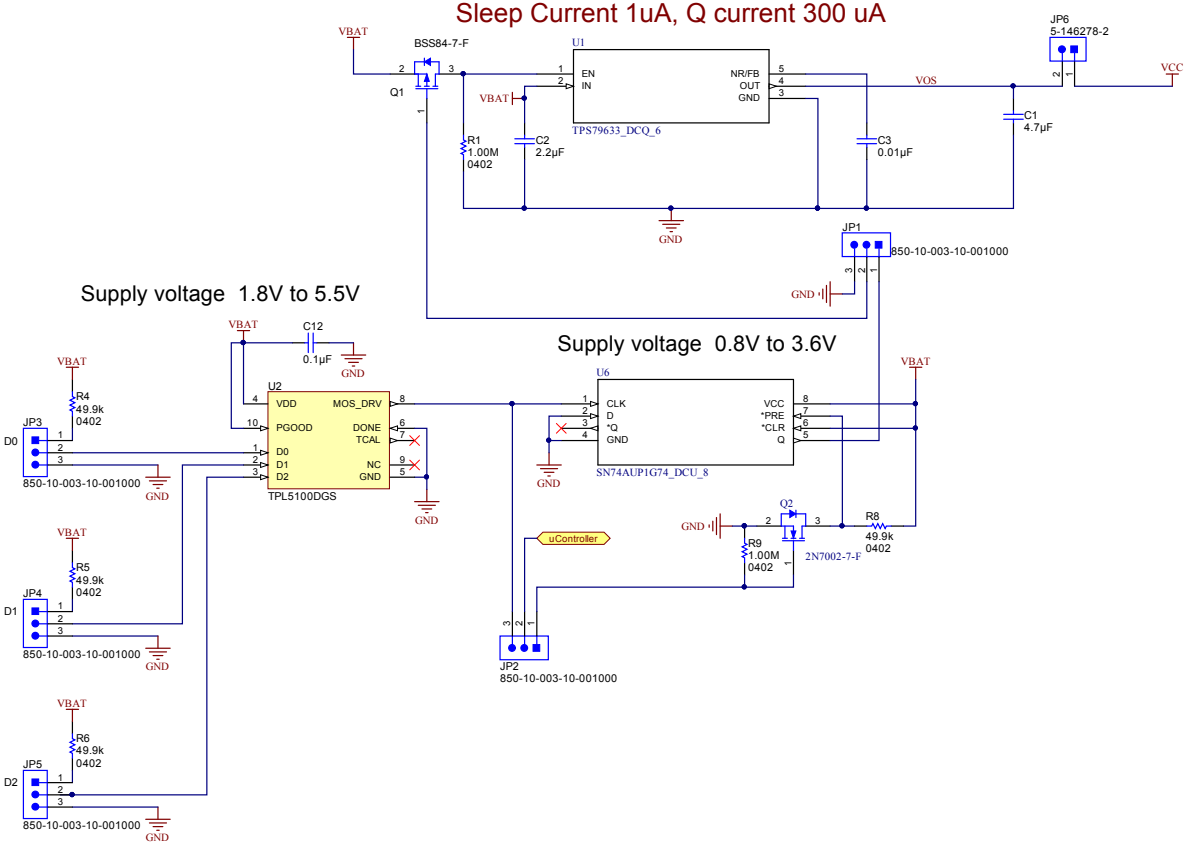
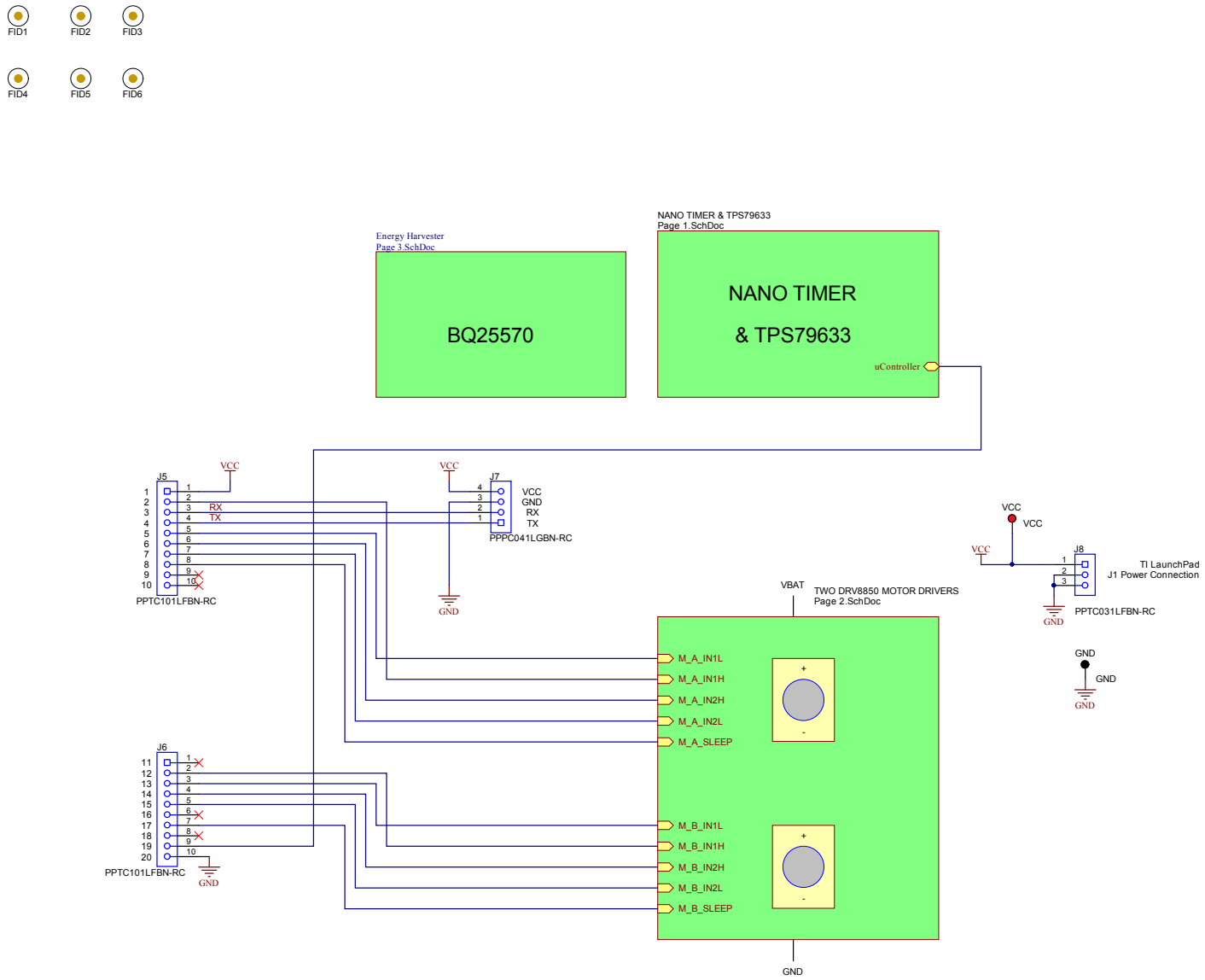
Input Voltage Range 2.7 to 5.5V

Sleep Current 1uA, Q current 300 uA



Orderable: N/A	Designed for:Public Release	Mod. Date: 7/23/2015
TID #:	Project Title:IoT Energy Harvesting BoosterPack	
Number: UTDBoosterPackRev: Rev2.5	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant:[No Variations]	Sheet:2 of 3
Drawn By:	File: Page 1.SchDoc	Size: B
Engineer: Ahmad Rashed	Contact: http://www.ti.com/support	

Texas Instruments
http://www.ti.com



Orderable: N/A	Designed for:Public Release	Mod. Date: 7/23/2015
TID #:	Project Title:IoT Energy Harvesting BoosterPack	
Number: UTDBoosterPack_R	Rev: Rev2.5	Sheet Title:
SVN Rev: Not in version control	Assembly Variant:[No Variations]	Sheet:2 of 3
Drawn By:	File: Block Diagram.SchDoc	Size: B
Engineer: Ahmad Rashed	Contact: http://www.ti.com/support	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DESIGN INFORMATION

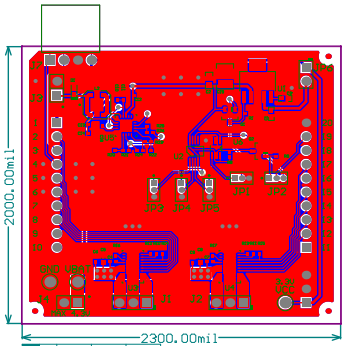
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: IoT Energy Harvesting BoosterPack
DESIGNED FOR: Public Release
FILE NAME: TID.PcbDoc
ENGINEER: Ahmad Rashed
LAYOUT BY: Ahmad Rashed
SCALE: 1.00
ALTIUM DESIGNER VERSION: 14.3.9.33548